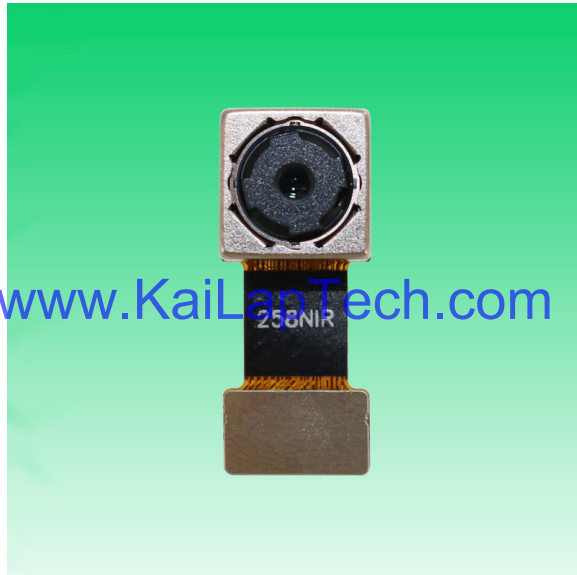


KLT-Z7MA-IMX258 V1.0 NIR

13MP Sony IMX258 MIPI Interface No IR Filter Auto Focus Camera Module



Front View



Back View

Specifications

Camera Module No.	KLT-Z7MA-IMX258 V1.0 NIR
Resolution	13MP
Image Sensor	IMX258
Sensor Type	1/3.06"
Pixel Size	1.12 um x 1.12 um
EFL	3.81 mm
F.NO	2.20
Pixel	4224 x 3136
View Angle	74.4°(DFOV) 62.7°(HFOV) 48.7°(VFOV)
Lens Dimensions	8.50 x 8.50 x 5.55 mm
Module Size	20.85 x 8.50 mm
Module Type	Auto Focus, No IR Filter Lens
Interface	MIPI
Auto Focus VCM Driver IC	DW9763
Lens Model	KLT-LENS-50013A1
Lens Type	650nm IR Cut
Operating Temperature	-20°C to +70°C
Mating Connector	AXE530124

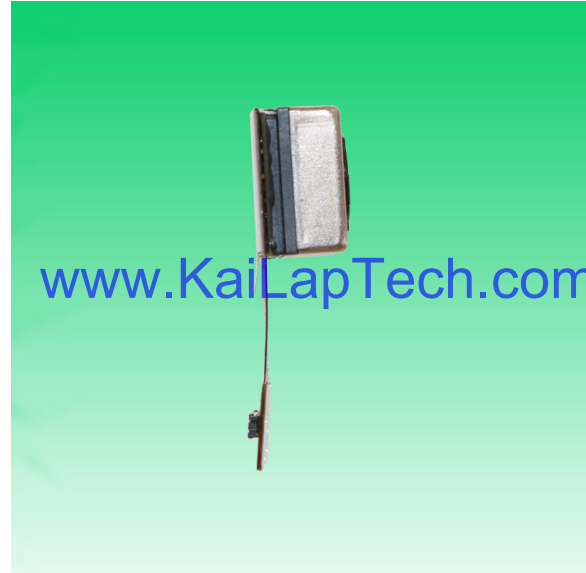


KLT-Z7MA-IMX258 V1.0 NIR

13MP Sony IMX258 MIPI Interface No IR Filter Auto Focus Camera Module



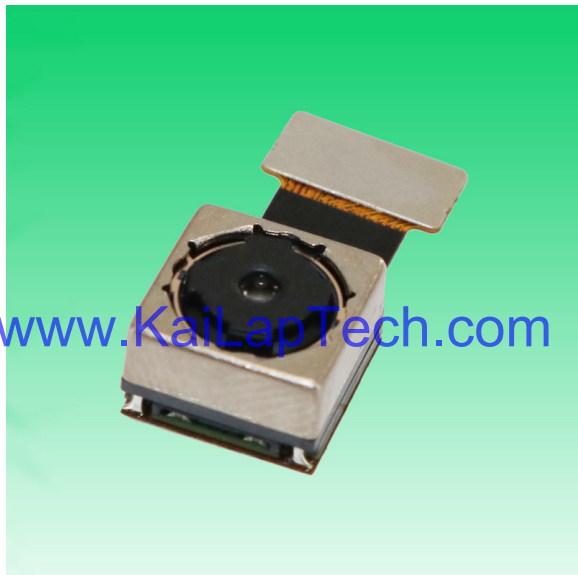
Top View



Side View

www.KaiLapTech.com

www.KaiLapTech.com

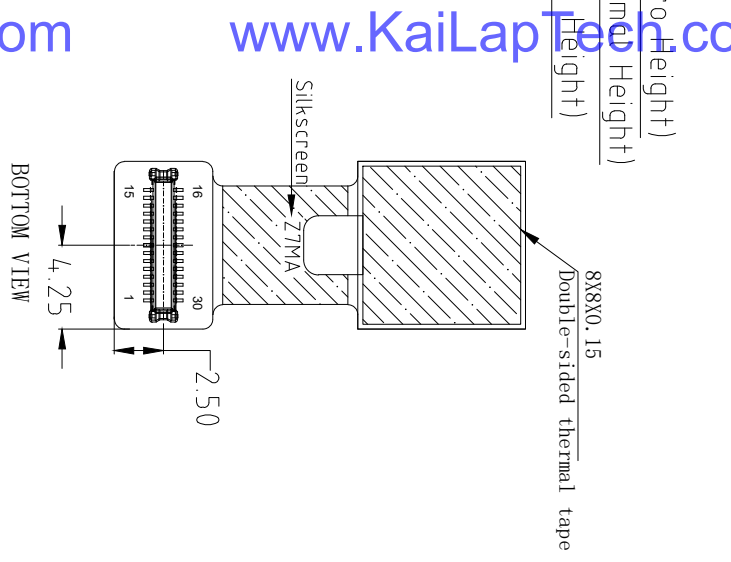
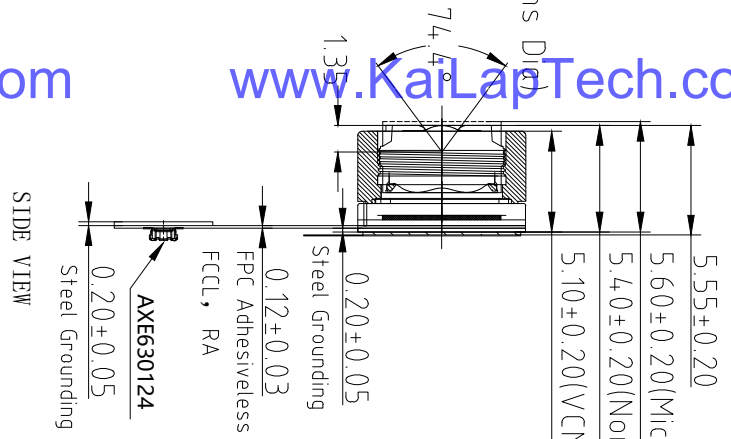
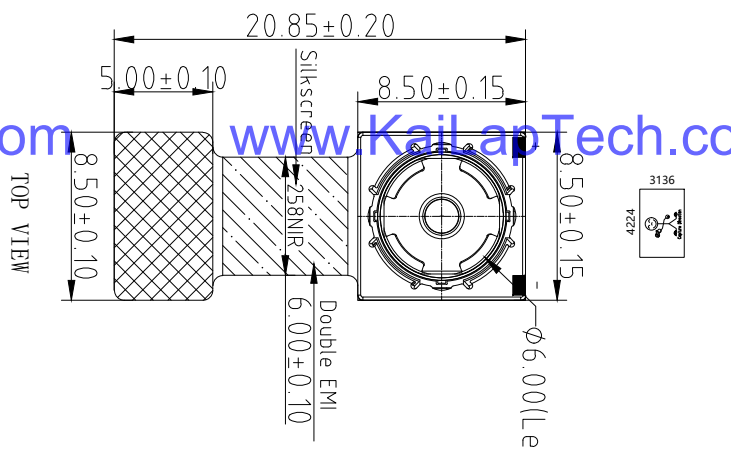


Bottom View



Mating Connector

A		B		C		D		E	
RoHS									
0	SIGNAL							Version	Information
1	DGND							V1.0	First Version
2	AF_GND								Date
3	SDA								7-7-2022
4	AFVDD 2.8V								
5	DOVDD 1.8V								
6	SCL								
7	AGND								
8	NC								
9	AVDD 2.8V								
10	DVDD 1.2V								
11	NC								
12	RST								
13	DGND								
14	MCLK								
15	DGND								
16	MD0P								
17	MD0N								
18	DGND								
19	MD3P								
20	MD3N								
21	DGND								
22	MCP								
23	MCN								
24	DGND								
25	MD1P								
26	MD1N								
27	DGND								
28	MD2P								
29	MD2N								
30	DGND								



NOTE:
 1.The device slave address:0x34;
 2.Driver IC and its I2C Address:
 DW9763; 0x18h;

Parameters:

1. Sensor specification:

Image Sensor: IMX258
 Pixel: 1.12um×1.12um
 Lens Type: 1/3.06
 Important Voltage Description: DVDD1.2V (external power supply);

2. Lens specification:

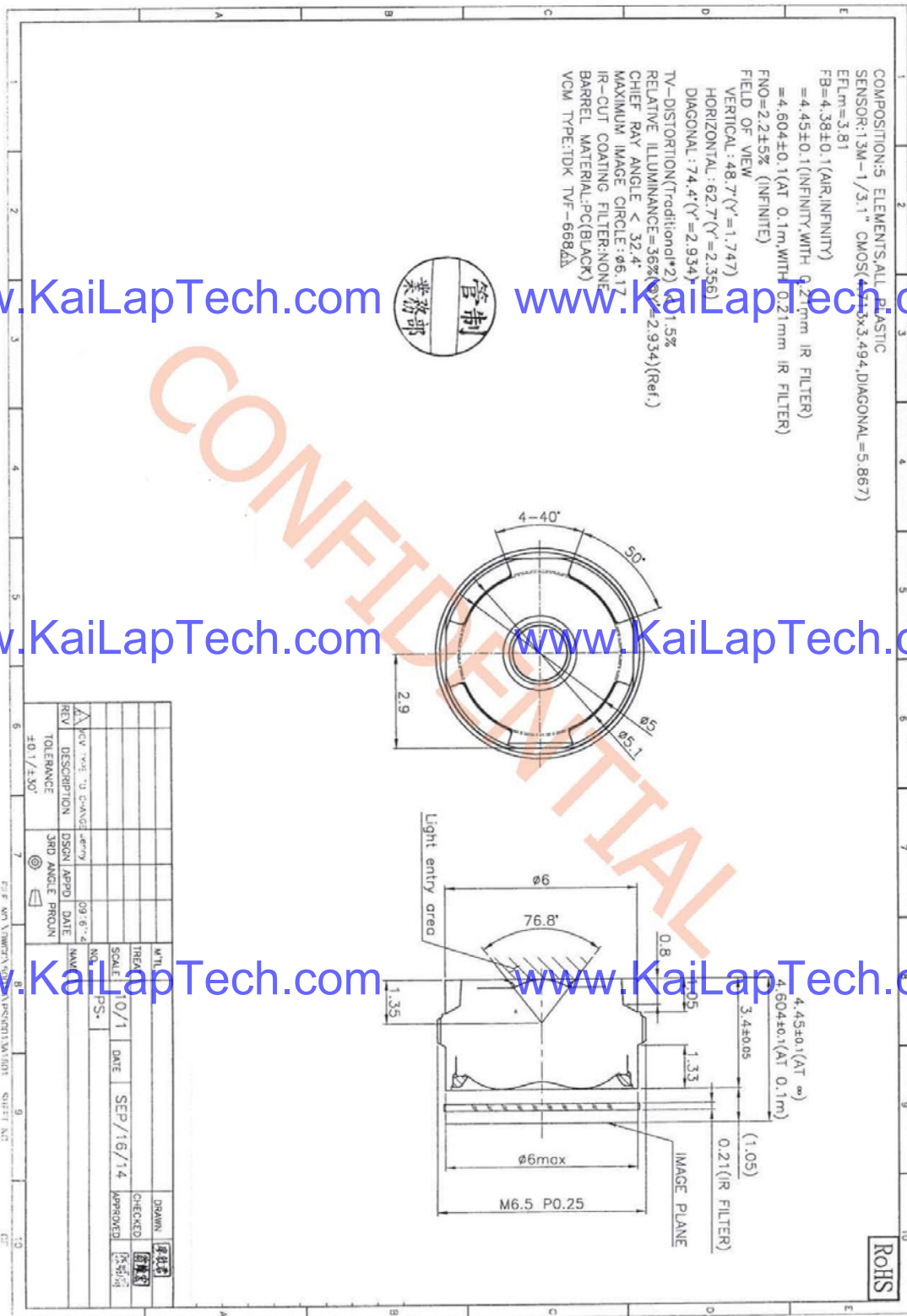
FOV: 74.4°(D);62.7°(H);48.7°(V)
 F/#: 2.2
 TVD distortion: <1.5%
 Focal length: 3.85mm
 Composition: 5P (NO IR FILTER)

Kai Lap Technologies Group Ltd

Designed By	Kevin	Model Name:	KLT-Z7MA-IMX258 V1.0 NIR		
Checked By	Aouly_Yan	Projection Type:	mm	Material:	-----
		Third Angle	Scale:	Sheet:	Version:
			1:1	1 of 1	1/0



Lens Model: KLT-LENS-50013A1



www.KaiLapTech.com

www.KaiLapTech.com

www.KaiLapTech.com

1. General Description

The DW9763 is a single 10-bit DAC with 100mA output current sinking capability and embedded 8KByte eFlash memory. Designed for linear control of voice coil motors, the DW9763 is capable of operating voltage up to 3.3V.

The SAC (Smart Actuator Control) mode is applied to minimize the mechanical vibration. The SAC mode highly improves the actuator's settling time and tolerance coverage compared with conventional LSC (Linear Slope Control) mode. The DAC and eFlash are controlled via an I2C compatible serial interface.

The DW9763 incorporates with a POR (Power On Reset) circuit, power down mode. POR circuit gets to operate when VDD (supply power) turns on. The output current keeps 0mA until valid register value takes place. During the power down mode, it consumes current max.1uA.

The DW9763 is designed for auto focus and optical zoom for mobile camera, digital still camera, camcorders and other nano actuator applications.

■ Features

- 10 bit resolution current sinking of 100mA for VCM
- SAC (Smart Actuator Control) mode
- Supply voltage range (VDD) : 2.3V to 3.3V
- Fast mode I2C interface compatible (1.8V interface available)
- Power down mode
- Power on reset (POR)
- Embedded 8KByte eFlash memory
- Package : 8 pin WLCSP
- Package Size : 0.77mm X 1.75mm X 0.3mm

www.KaiLapTech.com

www.KaiLapTech.com

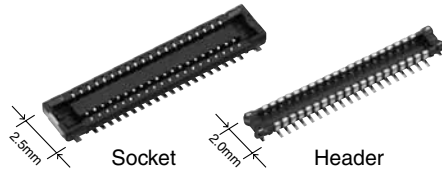
www.KaiLapTech.com

■ Applications

- Mobile camera
- Digital still camera
- Camcorder
- Web camera
- Nano actuator

www.KaiLapTech.com

www.KaiLapTech.com



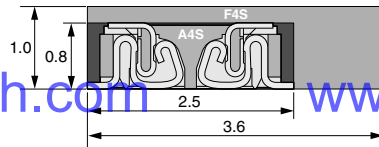
RoHS compliant

FEATURES

1. 2.5 mm wide slim two-piece style connectors

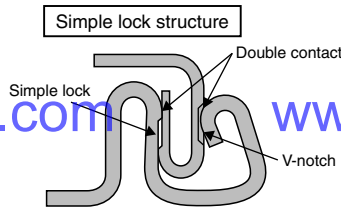
Compact and slim structure contributes overall miniaturization of product design. <Compared to F4S series (40 pin contacts, when mated)>

- Width: 30% down
- Footprint: 30% down



2. **"TOUGH CONTACT ADVANCED"** ensures high resistance to various environments in lieu of slim and low profile body

3. Simple lock structure provides tactile feedback to ensure excellent mating/unmating operation feel.



The connector gives the tactile feedback when inserted, allowing reliable mating.

- 4. Mated heights of 0.8 and 1.0 mm are available for the same foot pattern.
- 5. Connectors for inspection available

APPLICATIONS

Recommended for board-to-FPC connections of mobile equipment, such as cellular phones, smart phones, laptops, and portable music players

ORDERING INFORMATION

	AXE				2	4
5: Narrow Pitch Connector A4S (0.4 mm pitch) Socket						
6: Narrow Pitch Connector A4S (0.4 mm pitch) Header						
Number of pins (2 digits)						
Mated height						
<Socket>						
1: For mated height 0.8/1.0 mm						
<Header>						
1: For mated height 0.8 mm						
2: For mated height 1.0 mm						
Functions						
2: Without positioning bosses						
Surface treatment (Contact portion / Terminal portion)						
<Socket>						
4: Ni plating on base, Au plating on surface (for Ni barrier available)						
<Header>						
4: Ni plating on base, Au plating on surface						

PRODUCT TYPES

Mated height	Number of pins	Part number		Packing	
		Socket	Header	Inner carton (1-reel)	Outer carton
0.8mm	10	AXE510124	AXE610124	5,000 pieces	10,000 pieces
	12	AXE512124	AXE612124		
	14	AXE514124	AXE614124		
	16	AXE516124	AXE616124		
	18	AXE518124	AXE618124		
	20	AXE520124	AXE620124		
	22	AXE522124	AXE622124		
	24	AXE524124	AXE624124		
	26	AXE526124	AXE626124		
	28	AXE528124	AXE628124		
	30	AXE530124	AXE630124		
	32	AXE532124	AXE632124		
	34	AXE534124	AXE634124		
	36	AXE536124	AXE636124		
	38	AXE538124	AXE638124		
	40	AXE540124	AXE640124		
	44	AXE544124	AXE644124		
	50	AXE550124	AXE650124		
	54	AXE554124	AXE654124		
	56	AXE556124	AXE656124		
60	AXE560124	AXE660124			
64	AXE564124	AXE664124			
70	AXE570124	AXE670124			
80	AXE580124	AXE680124			
1.0mm	10	AXE510124	AXE610224	5,000 pieces	10,000 pieces
	12	AXE512124	AXE612224		
	14	AXE514124	AXE614224		
	20	AXE520124	AXE620224		
	24	AXE524124	AXE624224		
	26	AXE526124	AXE626224		
	30	AXE530124	AXE630224		
	32	AXE532124	AXE632224		
	40	AXE540124	AXE640224		
	44	AXE544124	AXE644224		
	50	AXE550124	AXE650224		
	54	AXE554124	AXE654224		
60	AXE560124	AXE660224			
70	AXE570124	AXE670224			
80	AXE580124	AXE680224			

- Notes: 1. Order unit:
 For volume production: 1-inner carton (1-reel) units
 Samples for mounting check: 50-connector units. Please contact our sales office.
 Samples: Small lot orders are possible. Please contact our sales office.
2. The above part numbers are for connectors without positioning bosses, which are standard. When ordering connectors with positioning bosses, please contact our sales office.
3. Please contact us for connectors having a number of pins other than those listed above.

www.KaiLapTech.com

www.KaiLapTech.com

AXE5, 6

SPECIFICATIONS

■ Characteristics

	Item	Specifications	Conditions
Electrical characteristics	Rated current	0.3A/pin contact (Max. 5 A at total pin contacts)	
	Rated voltage	60V AC/DC	
	Breakdown voltage	150V AC for 1 min.	No short-circuiting or damage at a detection current of 1 mA when the specified voltage is applied for one minute.
	Insulation resistance	Min. 1,000MΩ (initial)	Using 250V DC megger (applied for 1 min.)
	Contact resistance	Max. 90mΩ	Based on the contact resistance measurement method specified by JIS C 5402.
Mechanical characteristics	Composite insertion force	Max. 1.200N/pin contacts × pin contacts (initial)	
	Composite removal force	Min. 0.165N/pin contacts × pin contacts	
	Contact holding force (Socket contact)	Min. 0.20N/pin contacts	Measuring the maximum force. As the contact is axially pull out.
Environmental characteristics	Ambient temperature	-55°C to +85°C	No freezing at low temperatures. No dew condensation.
	Soldering heat resistance	Peak temperature: 260°C or less (on the surface of the PC board around the connector terminals) 300°C within 5 sec. 350°C within 3 sec.	Infrared reflow soldering Soldering iron
	Storage temperature	-55°C to +85°C (product only) -40°C to +50°C (emboss packing)	No freezing at low temperatures. No dew condensation.
	Thermal shock resistance (header and socket mated)	5 cycles, insulation resistance min. 100MΩ, contact resistance max. 90mΩ	Sequence 1. -55°C, 30 minutes 2. ~, Max. 5 minutes 3. 85°C, 30 minutes 4. ~, Max. 5 minutes
	Humidity resistance (header and socket mated)	120 hours, insulation resistance min. 100MΩ, contact resistance max. 90mΩ	Bath temperature 40±2°C, humidity 90 to 95% R.H.
	Saltwater spray resistance (header and socket mated)	24 hours, insulation resistance min. 100MΩ, contact resistance max. 90mΩ	Bath temperature 35±2°C, saltwater concentration 5±1%
	H ₂ S resistance (header and socket mated)	48 hours, contact resistance max. 90mΩ	Bath temperature 40±2°C, gas concentration 3±1 ppm, humidity 75 to 80% R.H.
	Lifetime characteristics	Insertion and removal life	30 times
Unit weight		20 pin contact type: Socket: 0.02 g Header: 0.01 g	

■ Material and surface treatment

Part name	Material	Surface treatment
Molded portion	LCP resin (UL94V-0)	—
Contact and Post	Copper alloy	Contact portion: Base: Ni plating Surface: Au plating Terminal portion: Base: Ni plating Surface: Au plating (except the terminal tips) The socket terminals close to the portion to be soldered have nickel barriers (exposed nickel portions). Soldering terminals: Sockets: Base: Ni plating Surface: Pd+Au flash plating (except the terminal tips) Headers: Base: Ni plating Surface: Au plating (except the terminal tips)

www.KaiLapTech.com

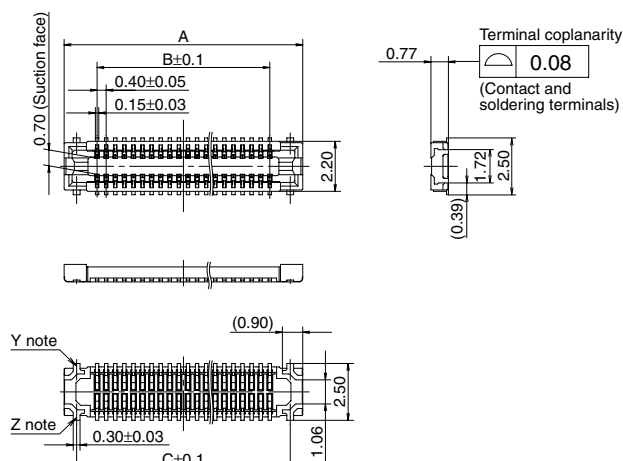
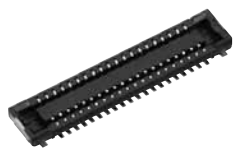
www.KaiLapTech.com

DIMENSIONS (Unit: mm)

The CAD data of the products with a **CAD Data** mark can be downloaded from: <http://industrial.panasonic.com/ac/e>

Socket (Mated height: 0.8 mm/1.0 mm)

CAD Data



Dimension table (mm)

Number of pins/ dimension	A	B	C
10	4.5	1.6	3.4
12	4.9	2.0	3.8
14	5.3	2.4	4.2
16	5.7	2.8	4.6
18	6.1	3.2	5.0
20	6.5	3.6	5.4
22	6.9	4.0	5.8
24	7.3	4.4	6.2
26	7.7	4.8	6.6
28	8.1	5.2	7.0
30	8.5	5.6	7.4
32	8.9	6.0	7.8
34	9.3	6.4	8.2
36	9.7	6.8	8.6
38	10.1	7.2	9.0
40	10.5	7.6	9.4
44	11.3	8.4	10.2
50	12.5	9.6	11.4
54	13.3	10.4	12.2
56	13.7	10.8	12.6
60	14.5	11.6	13.4
64	15.3	12.4	14.2
70	16.5	13.6	15.4
80	18.5	15.6	17.4

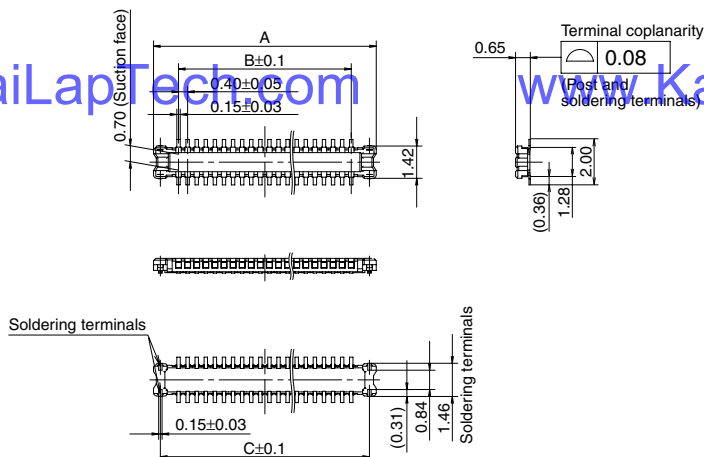
www.KaiLapTech.com

www.KaiLapTech.com
General tolerance: ±0.2

Note: Since the soldering terminals has a single-piece construction, sections Y and Z are electrically connected.

Header (Mated height: 0.8 mm)

CAD Data



Dimension table (mm)

Number of pins/ dimension	A	B	C
10	3.8	1.6	3.2
12	4.2	2.0	3.6
14	4.6	2.4	4.0
16	5.0	2.8	4.4
18	5.4	3.2	4.8
20	5.8	3.6	5.2
22	6.2	4.0	5.6
24	6.6	4.4	6.0
26	7.0	4.8	6.4
28	7.4	5.2	6.8
30	7.8	5.6	7.2
32	8.2	6.0	7.6
34	8.6	6.4	8.0
36	9.0	6.8	8.4
38	9.4	7.2	8.8
40	9.8	7.6	9.2
44	10.6	8.4	10.0
50	11.8	9.6	11.2
54	12.6	10.4	12.0
56	13.0	10.8	12.4
60	13.8	11.6	13.2
64	14.6	12.4	14.0
70	15.8	13.6	15.2
80	17.8	15.6	17.2

www.KaiLapTech.com

www.KaiLapTech.com
General tolerance: ±0.2

[Product Brief]

Ver.1.0

IMX258

Diagonal 5.867 mm (Type 1/3.06) 13Mega-Pixel CMOS Image Sensor with Square Pixel for Color Cameras

Description

IMX258 is a diagonal 5.867mm (Type 1/3.06) 13 Mega-pixel CMOS active pixel type stacked image sensor with a square pixel array. It adopts Exmor RSM technology to achieve high speed image capturing by column parallel A/D converter circuits and high sensitivity and low noise image (comparing with conventional CMOS image sensor) through the backside illuminated imaging pixel structure. R, G, and B pigment primary color mosaic filter is employed. By introducing spatially multiplexed exposure technology, high dynamic range still pictures and movies are achievable. It

equips an electronic shutter with variable integration time. It operates with three power supply voltages: analog 2.7 V, digital 1.2 V and 1.8 V for input/output interface and achieves low power consumption.

In addition, this product is designed for use in cellular phone and tablet pc. When using this for another application, Sony does not guarantee the quality and reliability of product. Therefore, don't use this for applications other than cellular phone and tablet pc. Consult your Sony sales representative if you have any questions.

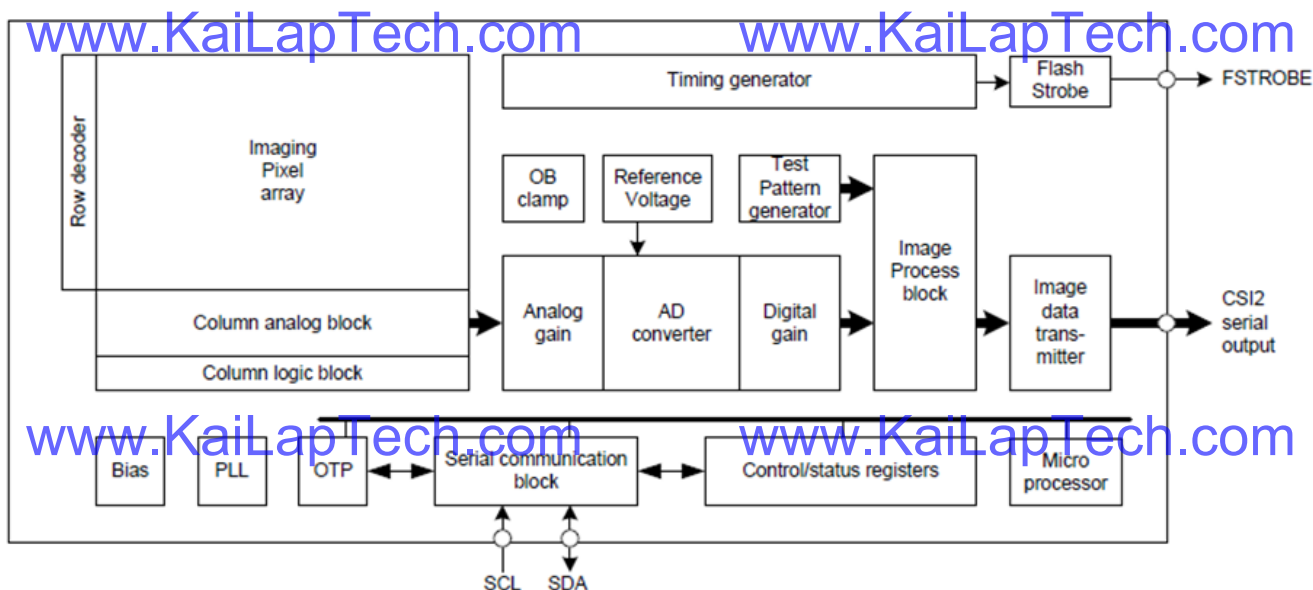
Functions and Features

- ◆ Back-illuminated and stacked CMOS image sensor Exmor RSM
- ◆ Phase Detection pixel data output for Phase Detection Auto Focus
- ◆ High Dynamic Range (HDR) mode with raw data output.
- ◆ High signal to noise ratio (SNR).
- ◆ Full resolution @30fps (Normal / HDR). 4K2K @30fps (Normal / HDR) 1080p @60fps (Normal)
- ◆ Output video format of RAW10/8.
- ◆ Pixel binning readout and V sub-sampling function.
- ◆ Independent flipping and mirroring.
- ◆ CSI-2 serial data output (MIPI 2lane/4lane, Max. 1.3Gbps/lane, D-PHY spec. ver. 1.1 compliant)
- ◆ 2-wire serial communication.
- ◆ Two PLLs for independent clock generation for pixel control and data output interface.
- ◆ Dynamic Defect Pixel Correction.
- ◆ Fast mode transition. (on the fly)
- ◆ Dual sensor synchronization operation.
- ◆ 4K bit of OTP ROM for users.
- ◆ Built-in temperature sensor.

Device Structure

- ◆ CMOS image sensor
- ◆ Image size : Diagonal 5.867 mm (Type 1/3.06)
- ◆ Total number of pixels : 4224 (H) × 3192 (V) approx. 13.48 M pixels
- ◆ Number of effective pixels : 4224 (H) × 3144 (V) approx. 13.28 M pixels
- ◆ Number of active pixels : 4208 (H) × 3120 (V) approx. 13.13 M pixels
- ◆ Chip size : 5.990 mm (H) × 3.908 mm (V)
- ◆ Unit cell size : 1.12 μm (H) × 1.12 μm (V)
- ◆ Substrate material : Silicon

System block diagram



www.KaiLapTech.com

www.KaiLapTech.com

Exmor RS

* Exmor RS is a trademark of Sony Corporation. The Exmor RS is a Sony's CMOS image sensor with high-resolution, high-performance and compact size by replacing a supporting substrate in Exmor R™ which changed fundamental structure of Exmor™ pixel adopted column parallel A/D converter to back-illuminated type, with layered chips formed signal processing circuits.



Camera Module Pinout Definition Reference Chart

OmniVision	Sony	Samsung	On-Semi	Aptina	Himax	GalaxyCore	PixArt	SmartSens	Sensors
Pin Signal		Description							
DGND GND		ground for digital circuit							
AGND		ground for analog circuit							
PCLK DCK		DVP PCLK output							
XCLR PWDN XSHUTDOWN STANDBY		power down active high with internal pull-down resistor							
MCLK XVCLK XCLK INCK		system input clock							
RESET RST		reset active low with internal pull-up resistor							
NC NULL		no connect							
SDA SIO_D SIOD		SCCB data							
SCL SIO_C SIOC		SCCB input clock							
VSYNC XVS FSYNC		DVP VSYNC output							
HREF XHS		DVP HREF output							
DOVDD		power for I/O circuit							
AFVDD		power for VCM circuit							
AVDD		power for analog circuit							
DVDD		power for digital circuit							
STROBE FSTROBE		strobe output							
FSIN		synchronize the VSYNC signal from the other sensor							
SID		SCCB last bit ID input							
ILPWM		mechanical shutter output indicator							
FREQ		frame exposure / mechanical shutter							
GPIO		general purpose inputs							
SLASEL		I2C slave address select							
AFEN		CEN chip enable active high on VCM driver IC							
MIPI Interface									
MDN0 DN0 MD0N DATA_N DMO1N		MIPI 1st data lane negative output							
MDP0 DP0 MD0P DATA_P DMO1P		MIPI 1st data lane positive output							
MDN1 DN1 MD1N DATA2_N DMO2N		MIPI 2nd data lane negative output							
MDP1 DP1 MD1P DATA2_P DMO2P		MIPI 2nd data lane positive output							
MDN2 DN2 MD2N DATA3_N DMO3N		MIPI 3rd data lane negative output							
MDP2 DP2 MD2P DATA3_P DMO3P		MIPI 3rd data lane positive output							
MDN3 DN3 MD3N DATA4_N DMO4N		MIPI 4th data lane negative output							
MDP3 DP3 MD3P DATA4_P DMO4P		MIPI 4th data lane positive output							
MCN CLKN CLK_N DCKN		MIPI clock negative output							
MCP CLKP MCP CLK_P DCKN		MIPI clock positive output							
DVP Parallel Interface									
D0 DO0 Y0		DVP data output port 0							
D1 DO1 Y1		DVP data output port 1							
D2 DO2 Y2		DVP data output port 2							
D3 DO3 Y3		DVP data output port 3							
D4 DO4 Y4		DVP data output port 4							
D5 DO5 Y5		DVP data output port 5							
D6 DO6 Y6		DVP data output port 6							
D7 DO7 Y7		DVP data output port 7							
D8 DO8 Y8		DVP data output port 8							
D9 DO9 Y9		DVP data output port 9							
D10 DO10 Y10		DVP data output port 10							
D11 DO11 Y11		DVP data output port 11							



Cameras Applications

your BEST camera module partner



www.KaiLapTech.com



www.KaiLapTech.com



www.KaiLapTech.com

www.KaiLapTech.com



www.KaiLapTech.com



www.KaiLapTech.com





Camera Reliability Test

Reliability Inspection Item		Testing Method	Acceptance Criteria	
Category	Item			
Environmental	Storage Temperature	High 60°C 96 Hours	Temperature Chamber	No Abnormal Situation
		Low -20°C 96 Hours	Temperature Chamber	No Abnormal Situation
	Operation Temperature	High 60°C 24 Hours	Temperature Chamber	No Abnormal Situation
		Low -20°C 24 Hours	Temperature Chamber	No Abnormal Situation
	Humidity	60°C 80% 24 Hours	Temperature Chamber	No Abnormal Situation
	Thermal Shock	High 60°C 0.5 Hours Low -20°C 0.5 Hours Cycling in 24 Hours	Temperature Chamber	No Abnormal Situation
Physical	Drop Test (Free Falling)	Without Package 60cm	10 Times on Wood Floor	Electrically Functional
		With Package 60cm	10 Times on Wood Floor	Electrically Functional
	Vibration Test	50Hz X-Axis 2mm 30min	Vibration Table	Electrically Functional
		50Hz Y-Axis 2mm 30min	Vibration Table	Electrically Functional
		50Hz Z-Axis 2mm 30min	Vibration Table	Electrically Functional
Cable Tensile Strength Test	Loading Weight 4 kg 60 Seconds Cycling in 24 Hours	Tensile Testing Machine	Electrically Functional	
Electrical	ESD Test	Contact Discharge 2 KV	ESD Testing Machine	Electrically Functional
		Air Discharge 4 KV	ESD Testing Machine	Electrically Functional
	Aging Test	On/Off 30 Seconds Cycling in 24 Hours	Power Switch	Electrically Functional
	USB Connector	On/Off 250 Times	Plug and Unplug	Electrically Functional





Inspection Item		Inspection Method	Standard of Inspection	
Category	Item			
Appearance	FPC/ PCB	Color	The Naked Eye	Major Difference is Not Allowed.
		Be Torn/Chopped	The Naked Eye	Copper Crack Exposure is Not Allowed.
		Marking	The Naked Eye	Clear, Recognizable (Within 30cm Distance)
	Holder	Scratches	The Naked Eye	The Inside Crack Exposure is Not Allowed
		Gap	The Naked Eye	Meet the Height Standard
		Screw	The Naked Eye	Make Sure Screws Are Presented (If Any)
		Damage	The Naked Eye	The Inside Crack Exposure is Not Allowed
	Lens	Scratch	The Naked Eye	No Effect On Resolution Standard
		Contamination	The Naked Eye	No Effect On Resolution Standard
		Oil Film	The Naked Eye	No Effect On Resolution Standard
		Cover Tape	The Naked Eye	No Issue On Appearance.
	Function	Image	No Communication	Test Board
Bright Pixel			Black Board	Not Allowed In the Image Center
Dark Pixel			White board	Not Allowed In the Image Center
Blurry			The Naked Eye	Not Allowed
No Image			The Naked Eye	Not Allowed
Vertical Line			The Naked Eye	Not Allowed
Horizontal Line			The Naked Eye	Not Allowed
Light Leakage			The Naked Eye	Not Allowed
Blinking Image			The Naked Eye	Not Allowed
Bruise			Inspection Jig	Not Allowed
Resolution			Chart	Follows Outgoing Inspection Chart Standard
Color			The Naked Eye	No Issue
Noise			The Naked Eye	Not Allowed
Corner Dark			The Naked Eye	Less Than 100px By 100px
Color Resolution			The Naked Eye	No Issue
Dimension	Height	The Naked Eye	Follows Approval Data Sheet	
	Width	The Naked Eye	Follows Approval Data Sheet	
	Length	The Naked Eye	Follows Approval Data Sheet	
	Overall	The Naked Eye	Follows Approval Data Sheet	



KLT Package Solutions

KLT Camera Module



Complete with Lens Protection Film



Tray with Grid and Space



Place Cameras on the Tray





Camera Modules Package Solution

Full Tray of Cameras



Cover Tray with Lid



Put Tray into Anti-Static Bag



Vacuum the Anti-Static Bag





Camera Modules Package Solution

Sealed Vacuum Bag with Labels

- 1. Model and Description 2. Quantity 3. Shipping Date 4. Caution**





CMOS CAMERA MODULES



your BEST camera module partner

Large Order Package Solution

Place Foam Sheets Between Trays

Foam Sheets are Slightly Larger than Trays



www.KaiLapTech.com

www.KaiLapTech.com

Place Foam Sheets and Trays into Box

Foam Sheets are Tightly Fitting Box



www.KaiLapTech.com sales@KaiLapTech.com Tel: (852) 6908 1256 Fax: (852) 3017 6778

All rights reserved @ Kai Lap Technologies Group Ltd. Specifications subject to change without notice.



CMOS CAMERA MODULES



your BEST camera module partner

Small Order Package Solution

Place Foam Sheets and Trays into Small Box



www.KaiLapTech.com

Package in Small Box for Shipment

Foam Sheets are Nicely Fitting the Small Box



www.KaiLapTech.com

Place Small Boxes into Larger Box



www.KaiLapTech.com sales@KaiLapTech.com Tel: (852) 6908 1256 Fax: (852) 3017 6778

All rights reserved @ Kai Lap Technologies Group Ltd. Specifications subject to change without notice.



Carbon Box Package Solution

Seal the Carbon Box

Final Package Labelled Box



Carbon Box Ready for Shipment

1. Delivery Address and Phone No.
2. Box No. and Ship Date
3. Fragile Caution





Sample Order Package Solution

Place Sample into Small Anti-Static Bag



Place Connectors into Small Ant-Static Bag



Sample Labels on the Small Bag

1. Camera Module or Connector Model
2. Shipping Date and Quantity
3. Caution





Connectors Large Order Package Solution

Connectors in a Wheel



Label Connectors in the Wheel



The Wheel is Perfectly Fitting the Box



Connectors Box Ready for Shipment



Company Kai Lap Technologies (KLT)

Kai Lap Technologies Group Limited. (KLT) was established in 2009, a next-generation technology driven manufacturer specialized in research, design, and produce of audio and video products. KLT is occupying 20,000 square feet automated plants with 100 employees of annual throughput 30,000,000 units cameras.

KLT provides OEM, ODM design, contract manufacturing, and builds the camera products. You may provide the requirements to us, even with a hand draft, our sales and engineering work together to meet your needs. We consider ourselves your last-term partner in developing practical and innovative solutions.

Our team covers everything from initial concept development to mass produced product. KLT specializes in customized camera design, raw material, electronic engineering, firmware/software development, product testing, and packing design. Our experienced strategic supply systems offer a robust and dependable manufacturing capacity for orders of various sizes.

www.KaiLapTech.com

www.KaiLapTech.com



Limited Warranty

KLT provides the following limited warranty if you purchased the Product(s) directly from KLT company or from KLT's website, www.KaiLapTech.com. Product(s) purchased from other sellers or sources are not covered by this Limited Warranty. KLT guarantees that the Product(s) will be free from defects in materials and workmanship under normal use for a period of one (1) year from the date you receive the product ("Warranty Period").

For all Product(s) that contain or develop material defects in materials or workmanship during the Warranty Period, KLT will, at its sole option, either: (i) repair the Product(s); (ii) replace the Product(s) with a new or refurbished Product(s) (replacement Product(s) being of identical model or functional equivalent); or (iii) provide you a refund of the price you paid for the Product(s).

This Limited Warranty of KLT is solely limited to repair and/or replacement on the terms set forth above. KLT is not reliable or responsible for any subsequent events.





CMOS CAMERA MODULES



your BEST camera module partner

KLT Strength

Powerful Factory



www.KaiLapTech.com

www.KaiLapTech.com

Professional Service



www.KaiLapTech.com

www.KaiLapTech.com

Promised Delivery



www.KaiLapTech.com

www.KaiLapTech.com



www.KaiLapTech.com sales@KaiLapTech.com Tel: (852) 6908 1256 Fax: (852) 3017 6778

All rights reserved @ Kai Lap Technologies Group Ltd. Specifications subject to change without notice.